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(71) Applicant: **SEGUENTE, INC.** [US/US]; 1333 Gateway Drive, Suite 1002, Melbourne, FL 32901 (US).

(72) Inventors: **AMALFI, Raffaele, Luca**; 6826 Crooked Stick Drive, Apt. 1408, Melbourne, FL 32940 (US). **ENRIGHT, Ryan**; 76 Briarwood Drive East, Berkeley Heights, NJ 07922 (US). **KIM, John**; 26 Hoagland Court, Bridgewater, NJ 08807 (US).

(74) Agent: **STEINBERGER, Brian, S.**; Law Offices of Brian S. Steinberger, 101 Brevard Avenue, Cocoa, FL 32922 (US).

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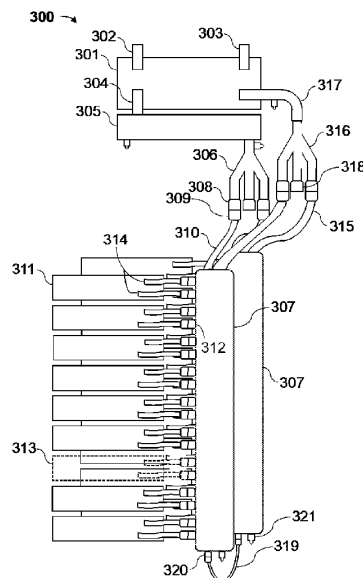


FIG. 3
(Schematic of the two-phase cooling system.)

(57) Abstract: Systems, devices and methods for providing cooling to hardware components, and more specifically to manifold systems, devices and methods for thermal management of hardware in computer server racks and related equipment in computer data centers.

[Continued on next page]

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